

Method for bonding substrates

Abstract

The present invention relates to a method for bonding a first substrate (2) with a second substrate (2') at contact faces (2o, 2o') of the substrates (2, 2') with the following steps, in particular the following sequence:

- holding of the first substrate (2) to a first sample holder surface (1o) of a first sample holder (1) with a holding force F_{H1} and holding of the second substrate (2') to a second sample holder surface (1o') of a second sample holder (1') with a holding force F_{H2} ,
- contacting of the contact faces (2o, 2o') at a bond initiation point (20) and heating of at least the second sample holder surface (1o, 1o') to a heating temperature T_H ,
- bonding of the first substrate (2) with the second substrate (2') along a bonding wave running from the bond initiation point (20) to the side edges (2s, 2s') of the substrates (2, 2'),

characterised in that

heating temperature T_H is reduced at the second sample holder surface (1o') during the bonding.

Figure 1d.